

## General Description

The WSD6056DN56 is the highest performance trench Dual N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSD6056DN56 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

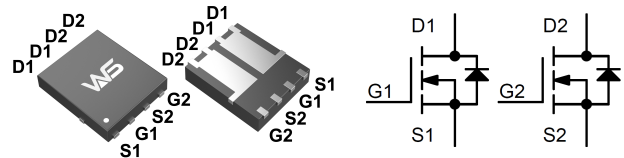
## Product Summary

| BVDSS | RDSON | ID  |
|-------|-------|-----|
| 60V   | 16mΩ  | 45A |

## Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Fast switching
- Load Switch

## DFN5X6C-8-EP2 Pin Configuration



## Absolute Maximum Ratings

| Symbol                | Parameter                              | Rating                          | Unit |
|-----------------------|--|---------------------------------|------|
| <b>Common Ratings</b> |  |                                 |      |
| $V_{DSS}$             | Drain-Source Voltage                   | 60                              | V    |
| $V_{GSS}$             | Gate-Source Voltage                    | ±20                             | V    |
| $T_J$                 | Maximum Junction Temperature           | 150                             | °C   |
| $T_{STG}$             | Storage Temperature Range              | -55 to 150                      | °C   |
| $I_S$                 | Diode Continuous Forward Current       | $T_c=25^\circ\text{C}$<br>45    | A    |
| $I_D$                 | Continuous Drain Current               | $T_c=25^\circ\text{C}$<br>45    | A    |
|                       |  | $T_c=70^\circ\text{C}$<br>28.5  |      |
| $I_{DM}^b$            | Pulse Drain Current Tested             | $T_c=25^\circ\text{C}$<br>180   | A    |
| $P_D$                 | Maximum Power Dissipation              | $T_c=25^\circ\text{C}$<br>67    | W    |
|                       |  | $T_c=70^\circ\text{C}$<br>45    |      |
| $R_{\theta JL}$       | Thermal Resistance-Junction to Lead    | Steady State<br>5               | °C/W |
| $R_{\theta JA}$       | Thermal Resistance-Junction to Ambient | $t \leq 10\text{s}$<br>45       | °C/W |
|                       |  | Steady State <sup>b</sup><br>90 |      |
| $I_{AS}^d$            | Avalanche Current, Single pulse        | $L=0.5\text{mH}$<br>20          | A    |
| $E_{AS}^d$            | Avalanche Energy, Single pulse         | $L=0.5\text{mH}$<br>20          | mJ   |

Note a : Max. continuous current is limited by bonding wire.

Note b : Pulse width limited by max. junction temperature.

Note c : Surface mounted on 1in<sup>2</sup> pad area, steady state  $t = 999\text{s}$ .

Note d : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature  $T_J=25^\circ\text{C}$ ).

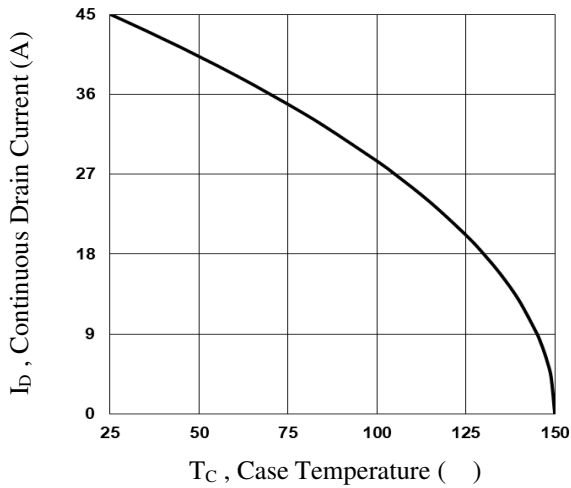
**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

| Symbol  | Parameter                        | Test Conditions  | Min. | Typ. | Max. | Unit |
|---|----------------------------------|--|------|------|------|------|
| <b>Static Characteristics</b>                     |                                  |  |      |      |      |      |
| BV <sub>DSS</sub>                                 | Drain-Source Breakdown Voltage   | V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA  | 60   | -    | -    | V    |
| I <sub>DSS</sub>                                  | Zero Gate Voltage Drain Current  | V <sub>DS</sub> =60V, V <sub>GS</sub> =0V<br>T <sub>J</sub> =85°C                                | -    | -    | 1    | μA   |
|   |                                  |  | -    | -    | 30   |      |
| V <sub>GS(th)</sub>                               | Gate Threshold Voltage           | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA  | 1.2  | 1.5  | 2.5  | V    |
| I <sub>GSS</sub>                                  | Gate Leakage Current             | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V   | -    | -    | ±100 | nA   |
| R <sub>DS(ON)</sub> <sup>3</sup>                  | Drain-Source On-state Resistance | V <sub>GS</sub> =10V, I <sub>DS</sub> =20A   | -    | 16   | 20   | mΩ   |
|   |                                  | V <sub>GS</sub> =4.5V, I <sub>DS</sub> =15A  | -    | 20   | 25   |      |
| <b>Diode Characteristics</b>                      |                                  |  |      |      |      |      |
| V <sub>SD</sub>                                   | Diode Forward Voltage            | I <sub>SD</sub> =1A, V <sub>GS</sub> =0V   | -    | 0.75 | 1.2  | V    |
| t <sub>rr</sub>                                   | Reverse Recovery Time            | I <sub>SD</sub> =20A, dI <sub>SD</sub> /dt=100A/μs   | -    | 26   | -    | ns   |
| Q <sub>rr</sub>                                   | Reverse Recovery Charge          |  | -    | 30   | -    | nC   |
| <b>Dynamic Characteristics</b> <sup>3,4</sup>     |                                  |  |      |      |      |      |
| R <sub>G</sub>                                    | Gate Resistance                  | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz   | -    | 0.9  | -    | Ω    |
| C <sub>iss</sub>                                  | Input Capacitance                | V <sub>GS</sub> =0V,<br>V <sub>DS</sub> =30V,<br>F=1.0MHz  | -    | 945  | -    | pF   |
| C <sub>oss</sub>                                  | Output Capacitance               |  | -    | 275  | -    |      |
| C <sub>riss</sub>                                 | Reverse Transfer Capacitance     |  | -    | 26   | -    |      |
| t <sub>d(ON)</sub>                                | Turn-on Delay Time               | V <sub>DD</sub> =30V,<br>I <sub>DS</sub> =1A,<br>V <sub>GEN</sub> =10V,<br>R <sub>G</sub> =3.3Ω. | -    | 10   | -    | ns   |
| t <sub>r</sub>                                    | Turn-on Rise Time                |  | -    | 13.5 | -    |      |
| t <sub>d(OFF)</sub>                               | Turn-off Delay Time              |  | -    | 28   | -    |      |
| t <sub>f</sub>                                    | Turn-off Fall Time               |  | -    | 20   | -    |      |
| <b>Gate Charge Characteristics</b> <sup>3,4</sup> |                                  |  |      |      |      |      |
| Q <sub>g</sub>                                    | Total Gate Charge                | V <sub>DS</sub> =30V,<br>V <sub>GS</sub> =10V, I <sub>DS</sub> =20A                              | -    | 28   | -    | nC   |
| Q <sub>g</sub>                                    | Total Gate Charge                | V <sub>DS</sub> =30V, V <sub>GS</sub> =10V,<br>I <sub>DS</sub> =20A                              | -    | 17.6 | -    |      |
| Q <sub>gth</sub>                                  | Threshold Gate Charge            |  | -    | 3.5  | -    |      |
| Q <sub>gs</sub>                                   | Gate-Source Charge               |  | -    | 2.7  | -    |      |
| Q <sub>gd</sub>                                   | Gate-Drain Charge                |  | -    | 6.3  | -    |      |

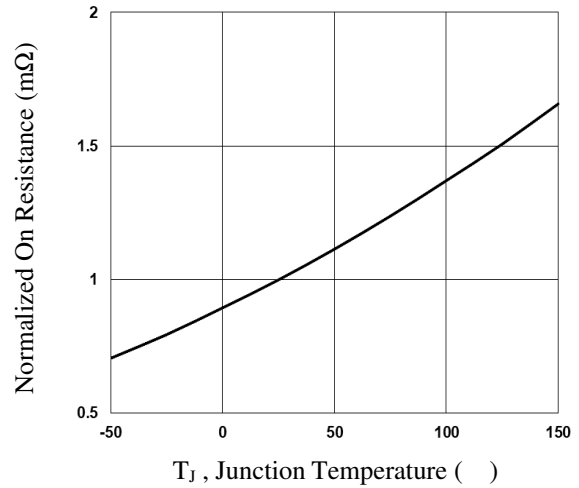
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=48V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=20A., R<sub>G</sub>=25Ω Starting T<sub>J</sub>=25
3. The data tested by pulsed , pulse width<=300us , duty cycle<=2%.
4. Essentially independent of operating temperature.

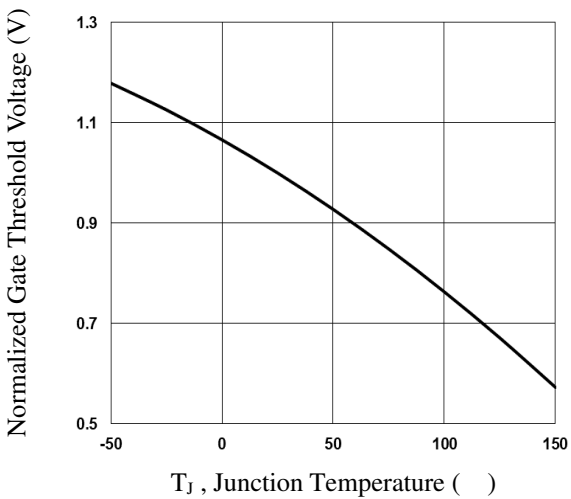
**Typical Operating Characteristics**



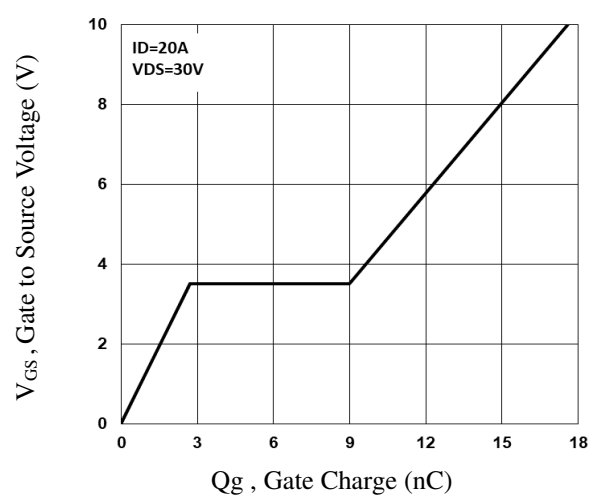
**Fig.1 Continuous Drain Current vs.  $T_c$**



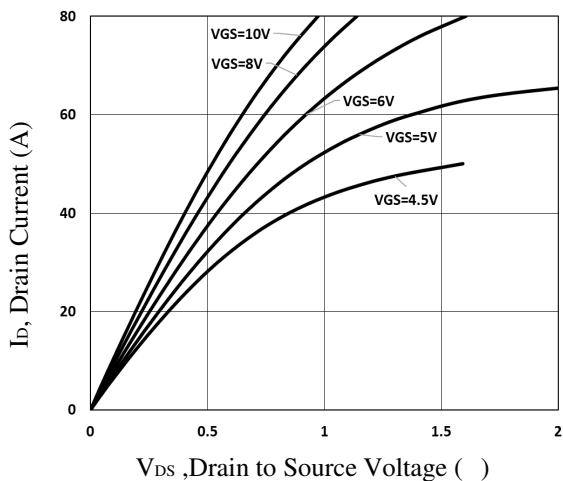
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



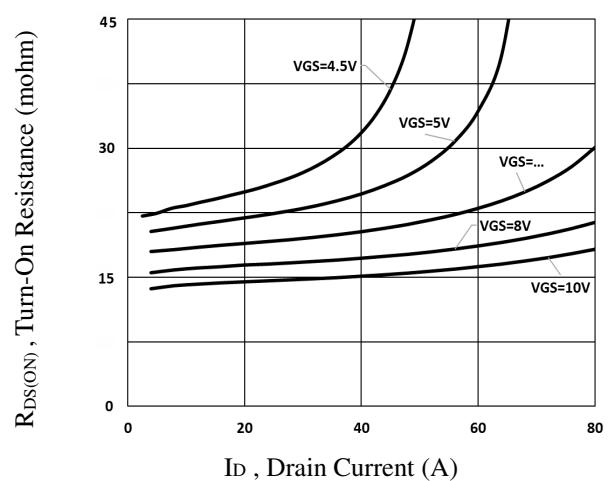
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



**Fig.4 Gate Charge Waveform**

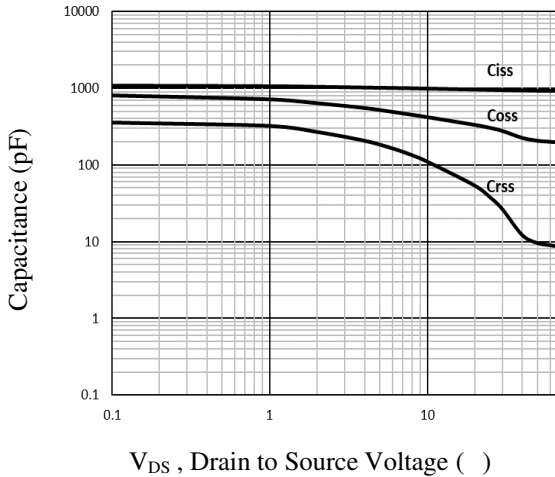


**Fig.5 Typical Output Characteristics**

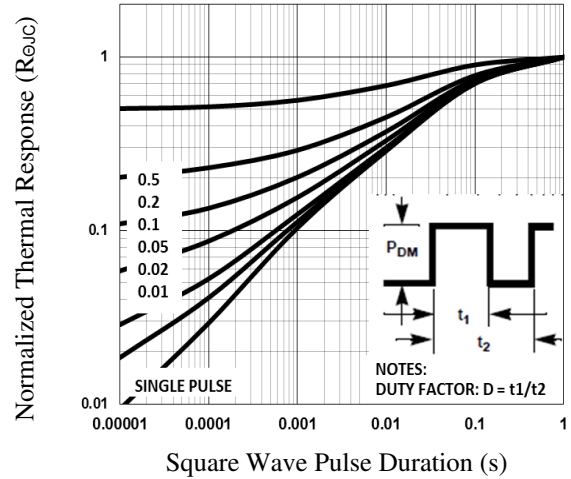


**Fig.6 Turn-On Resistance vs.  $I_D$**

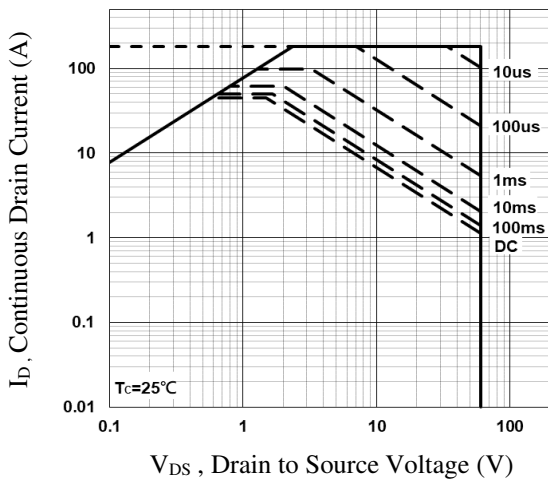
**Typical Operating Characteristics(Cont.)**



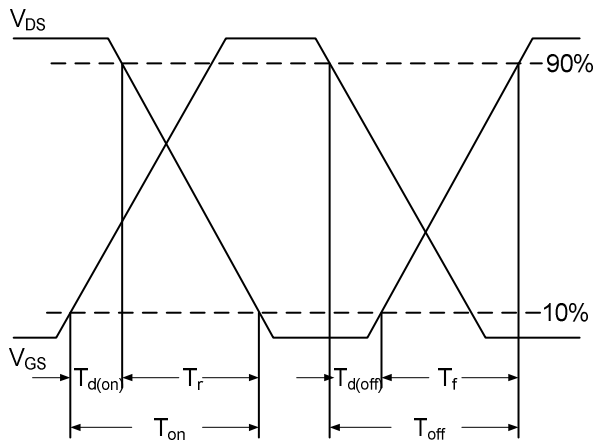
**Fig.7 Capacitance Characteristics**



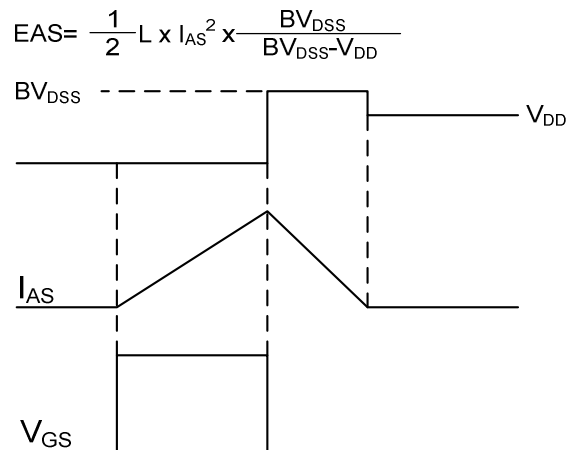
**Fig.8 Normalized Transient Response**



**Fig.9 Maximum Safe Operation Area**



**Fig.10 Switching Time Waveform**



**Fig.11 EAS Waveform**

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